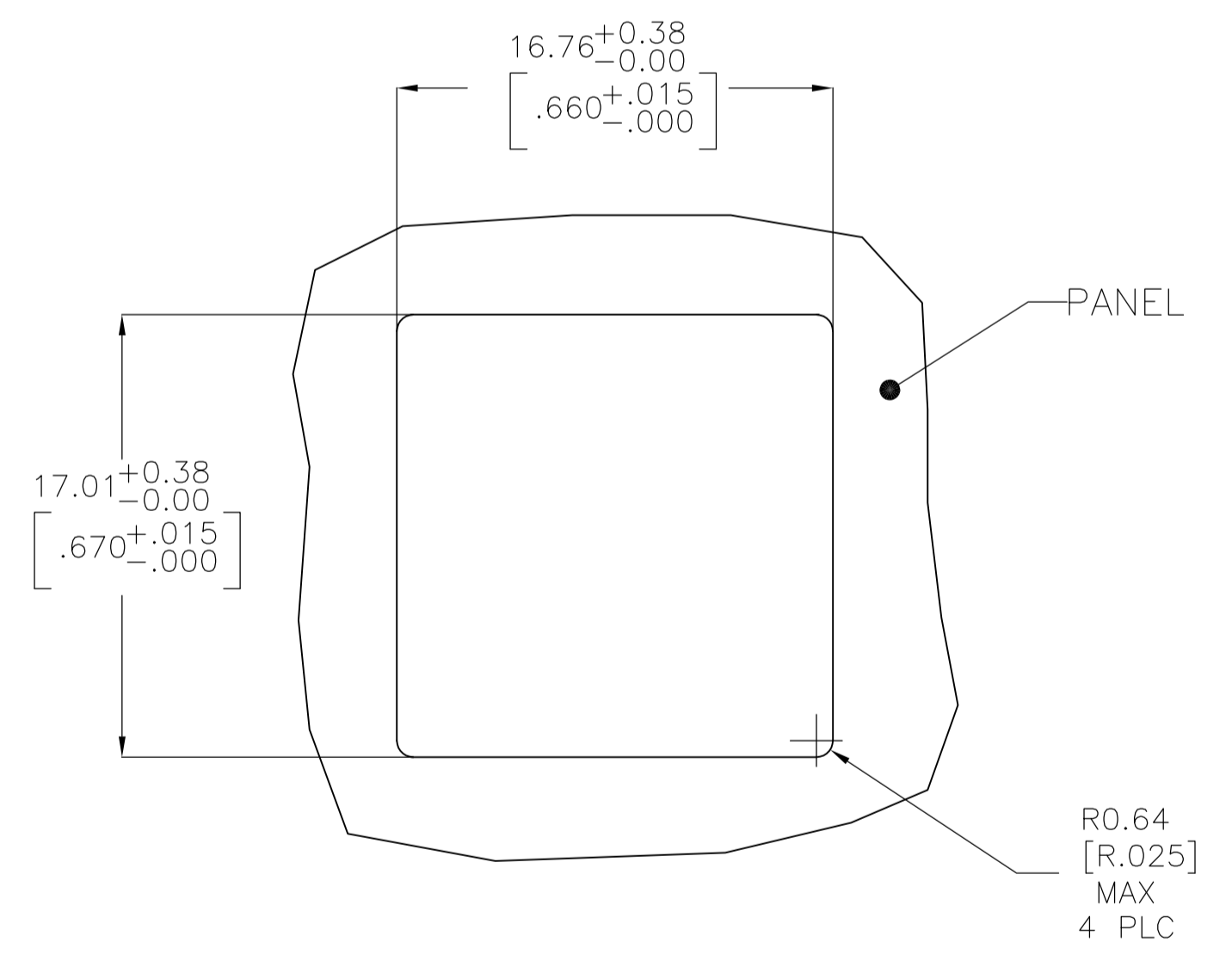


RECOMMENDED PRINTED
 CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL
 CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

1888412-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER/07MAR2006		Tyco Electronics Corporation	
DIMENSIONS: mm [INCHES]		CHK J.WESTMAN/07MAR2006		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.FLICKINGER/07MAR2006		NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	
0 PLC ± -		PRODUCT SPEC		108-1163	
1 PLC ± -		APPLICATION SPEC		114-2048	
2 PLC ± -		SIZE		A1	
3 PLC ± 0.13(.005)		CAGE CODE		00779	
4 PLC ± -		DRAWING NO		1888412	
ANGLES ± -		WEIGHT		-	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		CUSTOMER DRAWING	
		SCALE		4:1	
		SHEET		1 OF 1	
		REV		B	